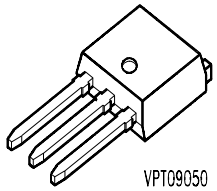
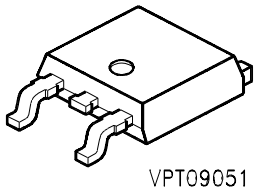
SIPMOS ® Power Transistor

- N channel
- Enhancement mode
- Avalanche-rated
- d*v*/d*t* rated
- 175°C operating temperature





Type	V_{DS}	I_D	$R_{DS(on)}$	Package	Ordering Code
SPD08N05L	55 V	8.4 A	0.18 Ω	P-TO252	Q67000-. . . . - . .
SPU08N05L	55 V	8.4 A	0.18 Ω	P-TO251	Q67000-. . . . - . .

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current	I_D		A
T_C = 25 °C		8.4	
T_C = 100 °C		5.9	
Pulsed drain current	I_{Dpuls}		
T_C = 25 °C		34	
Avalanche energy, single pulse	E_{AS}		mJ
I_D = 8.4 A, V_{DD} = 25 V, R_{GS} = 25 Ω			
L = 992 µH, T_j = 25 °C		35	
Avalanche current,limited by T_{jmax}	I_{AR}	8.4	A
Avalanche energy,periodic limited by T_{jmax}	E_{AR}	2.4	mJ
Reverse diode d*v*/d*t*	d*v*/d*t*		kV/µs
I_S = 8.4 A, V_{DS} = 40 V, di_F/dt = 200 A/µs			
T_{jmax} = 175 °C		6	
Gate source voltage	V_{GS}	± 14	V
Power dissipation	P_{tot}		W
T_C = 25 °C		24	

Maximum Ratings

Parameter	Symbol	Values	Unit
Operating temperature	T_j	-55 ... + 175	°C
Storage temperature	T_{stg}	-55 ... + 175	
Thermal resistance, junction - case	R_{thJC}	≤ 6.25	K/W
Thermal resistance, junction - ambient (PCB mount)**	R_{thJA}	≤ 50	
Thermal resistance, junction - ambient	R_{thJA}	≤ 100	
IEC climatic category, DIN IEC 68-1		55 / 175 / 56	

** when mounted on 1 " square PCB (FR4);for recommended footprint

Electrical Characteristics, at T_j = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage V_{GS} = 0 V, I_D = 0.25 mA, T_j = 25 °C	$V_{(BR)DSS}$	55	-	-	V
Gate threshold voltage V_{GS}=V_{DS}, I_D = 10 µA	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current V_{DS} = 50 V, V_{GS} = 0 V, T_j = -40 °C V_{DS} = 50 V, V_{GS} = 0 V, T_j = 25 °C V_{DS} = 50 V, V_{GS} = 0 V, T_j = 150 °C	I_{DSS}	 - -	 - 0.1	 0.1 1	µA
Gate-source leakage current V_{GS} = 20 V, V_{DS} = 0 V	I_{GSS}	-	10	100	nA
Drain-Source on-resistance V_{GS} = 4.5 V, I_D = 5.9 A	$R_{DS(on)}$	-	0.13	0.18	Ω

Electrical Characteristics, at T_j = 25°C, unless otherwise specified

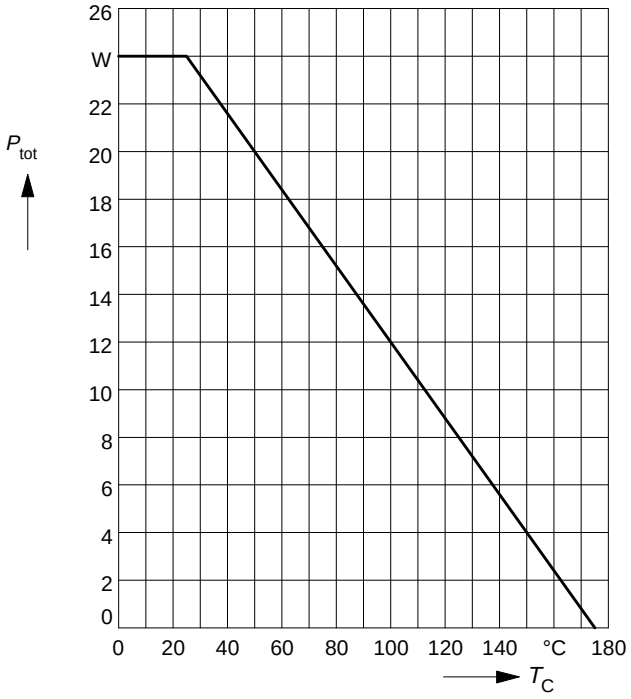
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}$, I_D = 5.9 A	g_{fs}	3	6.2	-	S
Input capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{iss}	-	250	315	pF
Output capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{oss}	-	80	100	
Reverse transfer capacitance V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	C_{rss}	-	45	56	
Turn-on delay time V_{DD} = 30 V, V_{GS} = 4.5 V, I_D = 8.4 A R_G = 25 Ω	$t_{d(on)}$	-	10	15	ns
Rise time V_{DD} = 30 V, V_{GS} = 4.5 V, I_D = 8.4 A R_G = 25 Ω	t_r	-	70	105	
Turn-off delay time V_{DD} = 30 V, V_{GS} = 4.5 V, I_D = 8.4 A R_G = 25 Ω	$t_{d(off)}$	-	14	22	
Fall time V_{DD} = 30 V, V_{GS} = 4.5 V, I_D = 8.4 A R_G = 25 Ω	t_f	-	14	22	
Gate charge at threshold V_{DD} = 40 V, I_D = 0.1 A, V_{GS} =0 to 1 V	$Q_{g(th)}$	-	0.25	0.38	nC
Gate charge at 5.0 V V_{DD} = 40 V, I_D = 8.4 A, V_{GS} =0 to 5 V	$Q_{g(5)}$	-	5	7.5	
Gate charge total V_{DD} = 40 V, I_D = 8.4 A, V_{GS} =0 to 10 V	$Q_{g(total)}$	-	9	14	
Gate plateau voltage V_{DD} = 40 V, I_D = 8.4 A	$V_{(plateau)}$	-	4	-	V

Electrical Characteristics, at T_j = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current T_C = 25 °C	I_S	-	-	8.4	A
Inverse diode direct current,pulsed T_C = 25 °C	I_{SM}	-	-	34	
Inverse diode forward voltage V_{GS} = 0 V, I_F = 16.8 A	V_{SD}	-	1.05	1.8	V
Reverse recovery time V_R = 30 V, I_F=I_S, di_F/dt = 100 A/µs	t_{rr}	-	50	75	ns
Reverse recovery charge V_R = 30 V, I_F=I_S, di_F/dt = 100 A/µs	Q_{rr}	-	0.085	0.13	µC

Power dissipation

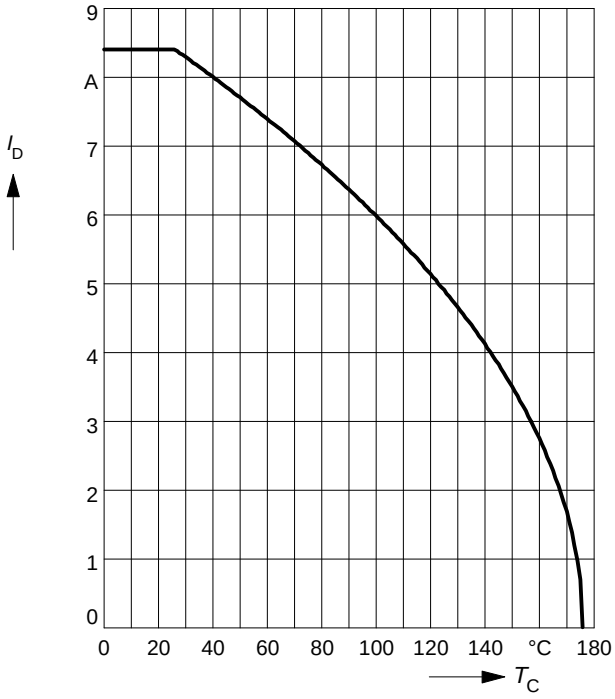
$P_{tot} = f(T_C)$



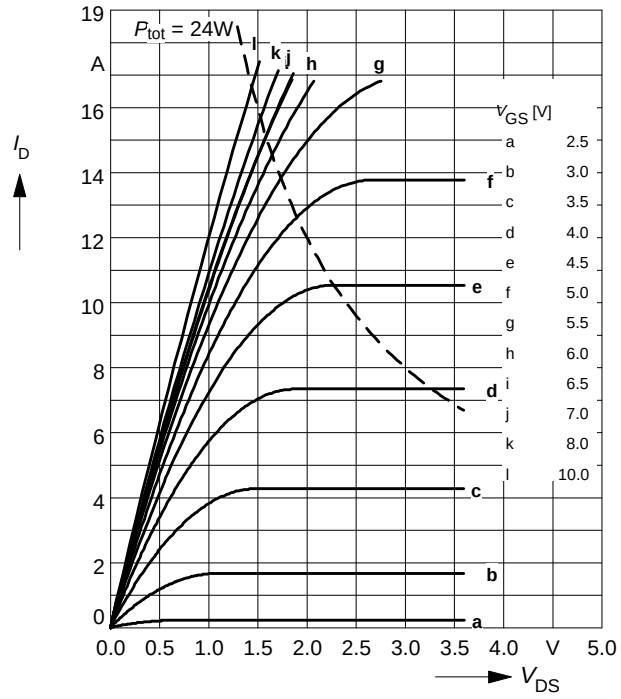
Drain current

$I_D = f(T_C)$

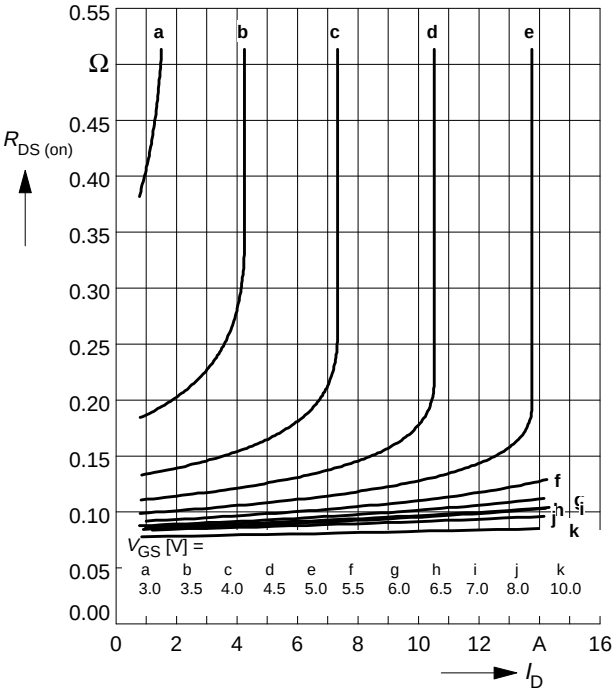
parameter: $V_{GS} \geq 4$ V



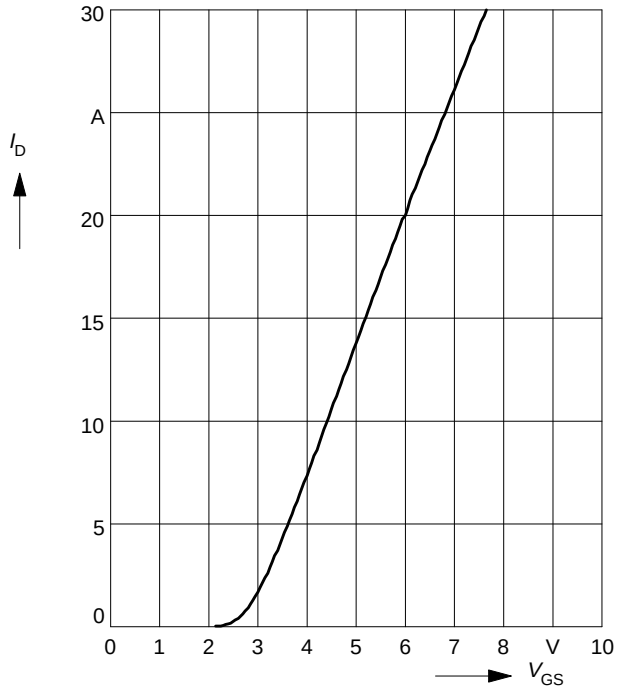
Typ. output characteristics
$I_D = f(V_{DS})$
parameter: t_p = 80 µs



Typ. drain-source on-resistance
$R_{DS\,(on)} = f(I_D)$
parameter: t_p = 80 µs, T_j = 25 °C

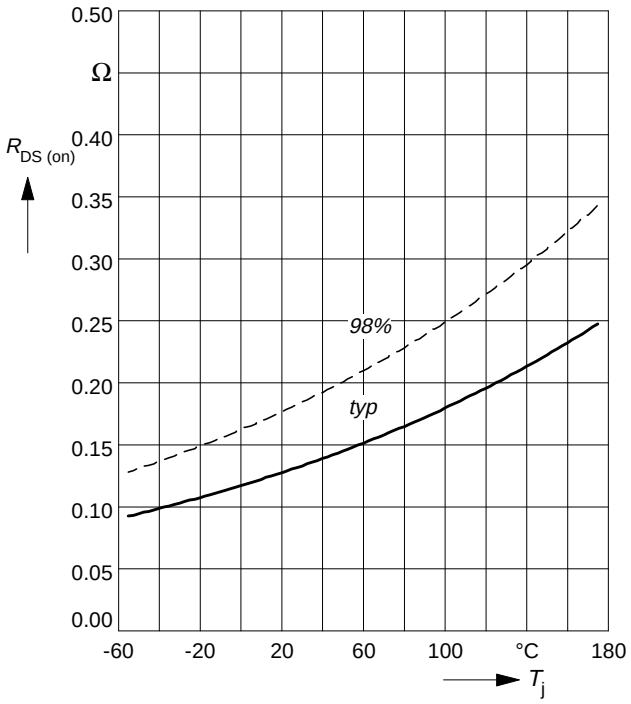


Typ. transfer characteristics $I_D = f(V_{GS})$
parameter: t_p = 80 µs
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



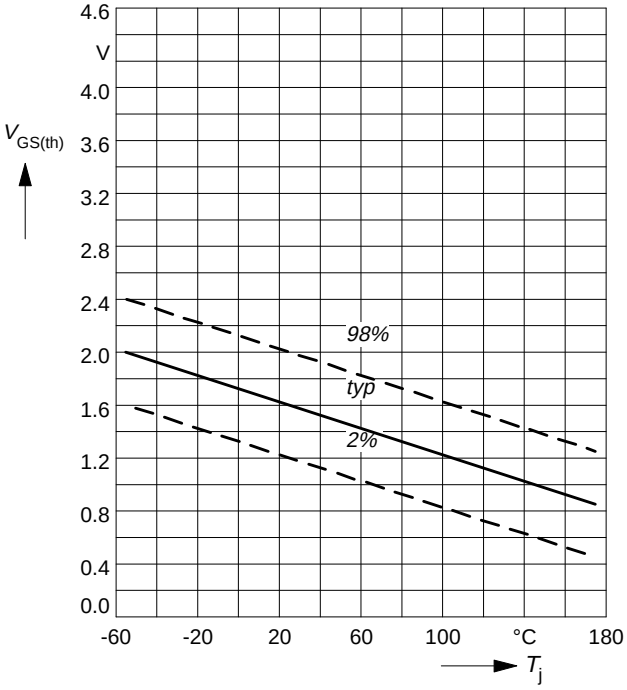
Drain-source on-resistance

$R_{DS\,(on)} = f(T_j)$
parameter: I_D = 5.9 A, V_{GS} = 4.5 V



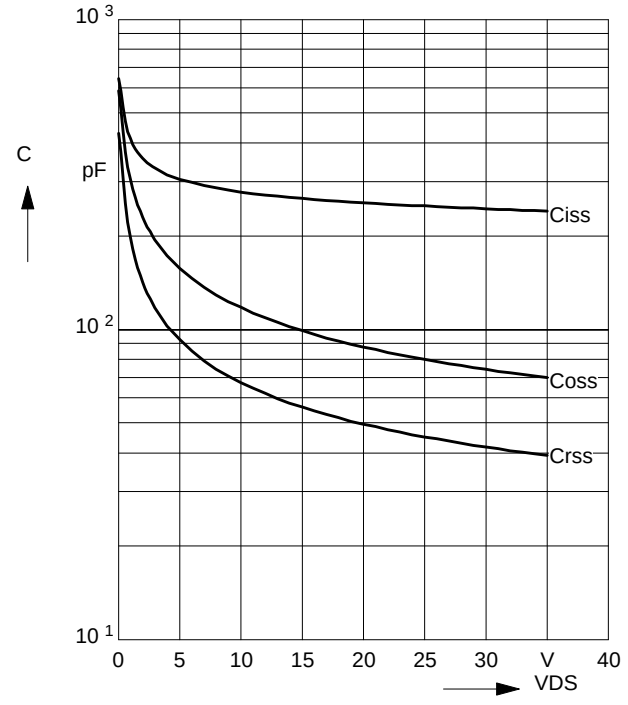
Gate threshold voltage

$V_{GS\,(th)} = f(T_j)$
parameter: $V_{GS} = V_{DS}$, I_D = 10 µA



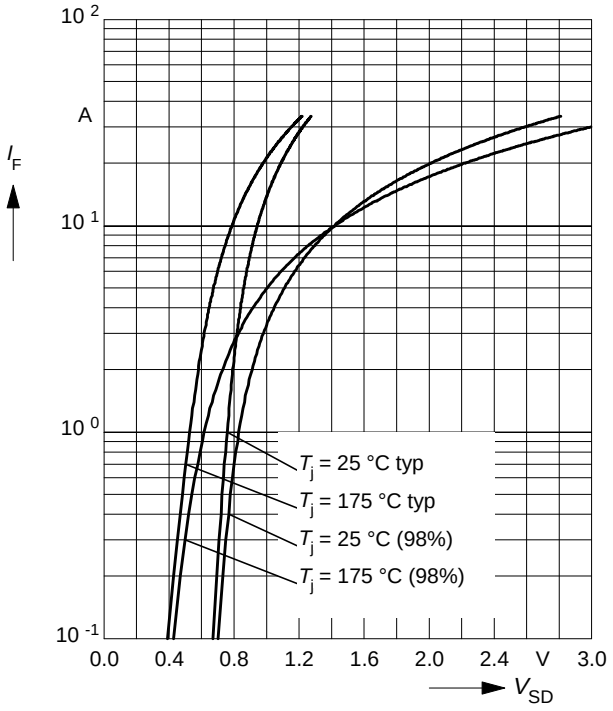
Typ. capacitances

$C = f(V_{DS})$
parameter: V_{GS} = 0V, f = 1MHz

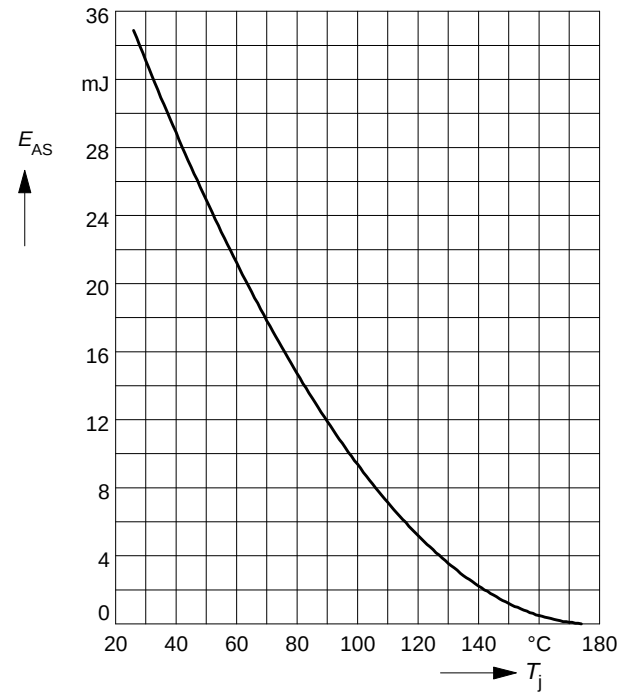


Forward characteristics of reverse diode

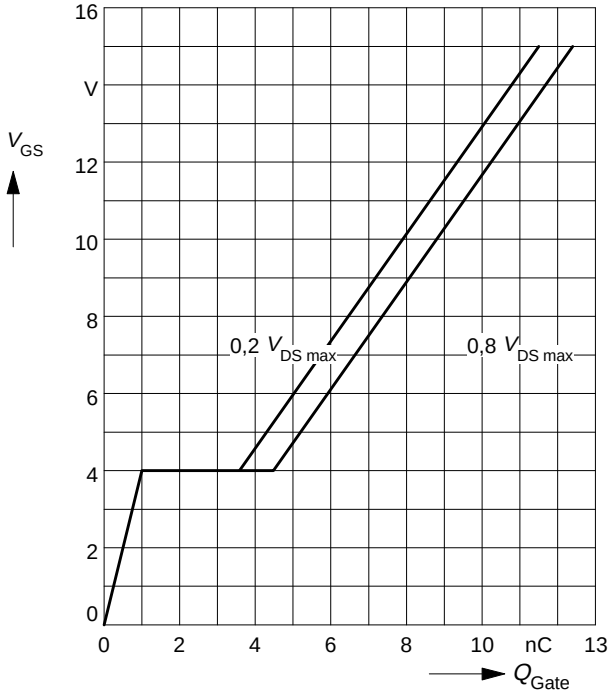
$I_F = f(V_{SD})$
parameter: T_j, t_p = 80 µs



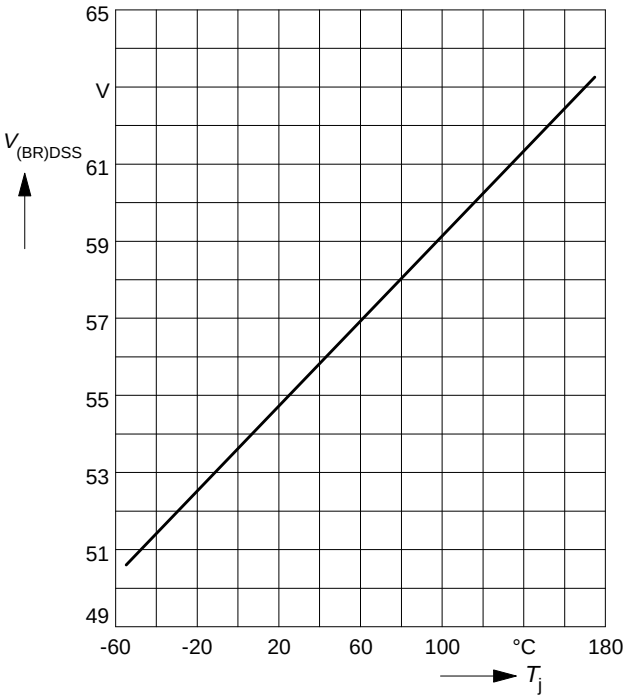
Avalanche energy $E_{AS} = f(T_j)$
parameter: I_D = 8.4 A, V_{DD} = 25 V
R_{GS} = 25 Ω, L = 992 µH



Typ. gate charge
$V_{GS} = f(Q_{Gate})$
parameter: $I_{D\ puls}$ = 8 A



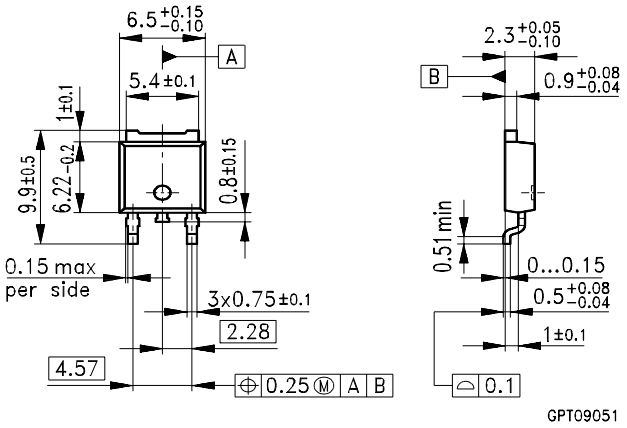
Drain-source breakdown voltage
$V_{(BR)DSS} = f(T_j)$



Package Outlines

P-TO252

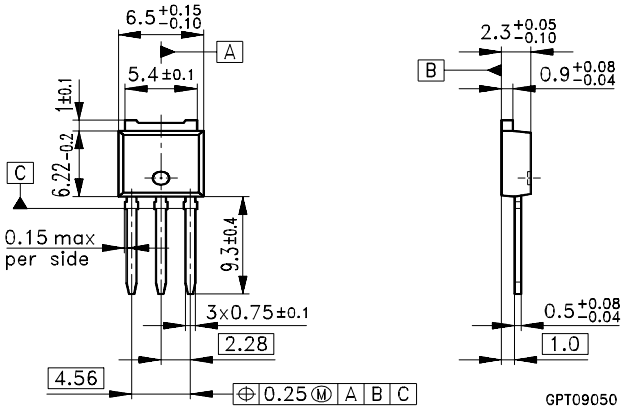
Dimension in mm



All metal surfaces tin plated, except area of cut.

P-TO251

Dimension in mm



All metal surfaces tin plated, except area of cut.